

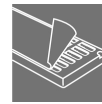
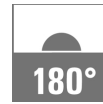
RJ45C6 R1V 3.2N4N TY**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com



The product range encompasses the following designs:

- 90°, lying (horizontal) and 180°, standing (vertical)
- latch up / latch down
- THT, THR or SMD soldering processes
- Wide range of different design types, also with integrated LEDs and shield contact tabs
- Performance category Cat. 3 to Cat. 6
- Packed either in a tray (TY) or on a roll (tape-on-reel, RL)
- Compatible with modular RJ45 connector according to ANSI / TIA-1096-A and IEC 60603
- Dielectric strength ≥ 1500 V AC RMS (2250 V AC peak value) according to IEEE 802.3
- Dielectric strength ≥ 1500 V AC (peak value) or ≥ 1500 V DC according to IEC 60603

Properties and advantages:

- Extended temperature range of -40°C to $+85^{\circ}\text{C}$ for maximum performance
- Reinforced gold layer ($30\mu\text{m}$) for improved corrosion protection
- At least 0.3mm stand-off ensures a perfect soldering result

General ordering data

Version	PCB plug-in connector, RJ45 jacks, Cat. 6 , THT/THR solder connection, 180°, LED: No, Number of poles: 8, Tray (manual assembly)
Order No.	2634590000
Type	RJ45C6 R1V 3.2N4N TY
GTIN (EAN)	4050118651270
Qty.	140 pc(s).
Packaging	Tray (manual assembly)

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Technical data

Dimensions and weights

Depth	16.7 mm	Depth (inches)	0.657 inch
Height	16.5 mm	Height (inches)	0.65 inch
Width	16 mm	Width (inches)	0.63 inch
Net weight	7.475 g		

System specifications

Category	Cat. 6	LED	No
Mounting onto the PCB	THT/THR solder connection	Number of poles	8
Outgoing elbow	180°	Performance-Category	Cat. 6
Pitch in inches (P)	0.05 "	Pitch in mm (P)	1.27 mm
Plugging cycles	750	Product family	OMNIMATE Data - RJ45 modular jack
Protection degree	IP20	Shield surface	nickel-plated
Shielding	Yes	Solder pin dimensions	Octagonal
Solder pin length (l)	3.2 mm	Soldering process	Reflow soldering, Manual soldering, Wave soldering
Tolerance of solder pin position	± 0.1 mm	Type of connection	Solder connection

Electrical properties

Dielectric strength, contact / contact	1000 V DC	Dielectric strength, contact / shield	1500 V DC
Insulation strength	≥ 500 MΩ	PoE / PoE+	conforming to IEEE 802.3at
Rated voltage	125 V		

Material data

Insulating material	PA 9T	Colour	black
Colour chart (similar)	RAL 9011	Insulation strength	≥ 500 MΩ
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact material	Cu-alloy	Contact surface	Gold over nickel
Operating temperature, min.	-40 °C	Operating temperature, max.	80 °C

Packing

Packaging	Tray (manual assembly)	VPE length	317 mm
VPE width	188 mm	VPE height	68 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ETIM 10.0	EC002637	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01
ECLASS 14.0	27-46-02-01	ECLASS 15.0	27-46-02-01

Environmental Product Compliance

RoHS Compliance Status	Compliant without exemption
REACH SVHC	No SVHC above 0.1 wt%

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Technical data

Approvals

ROHS	Conform
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Downloads

Approval/Certificate/Document of Con- formity	Certificate of Compliance
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Engineering Data	CAD data – STEP
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Catalogues	Catalogues in PDF-format
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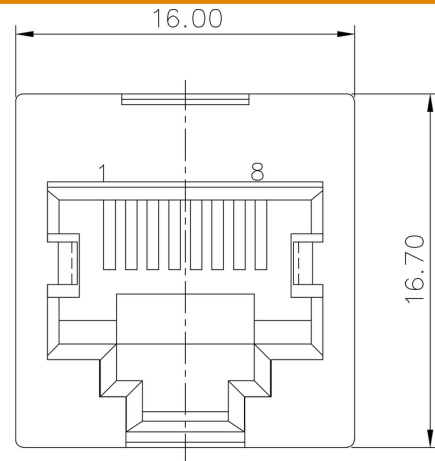
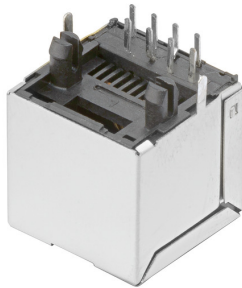
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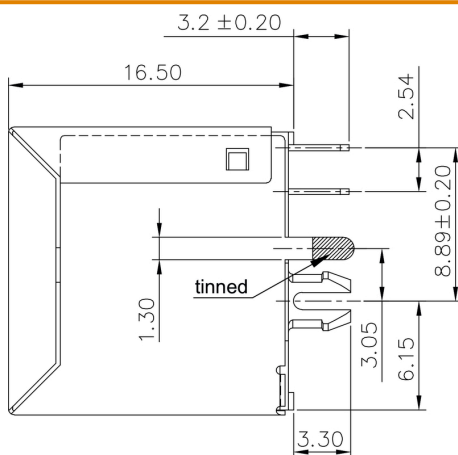
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Drawings

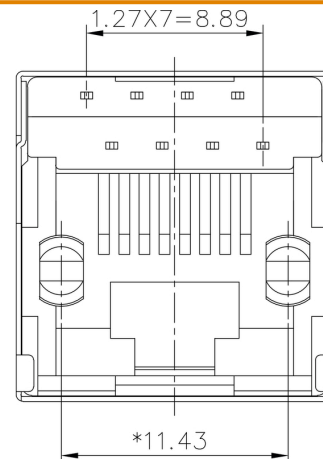
Dimensioned drawing



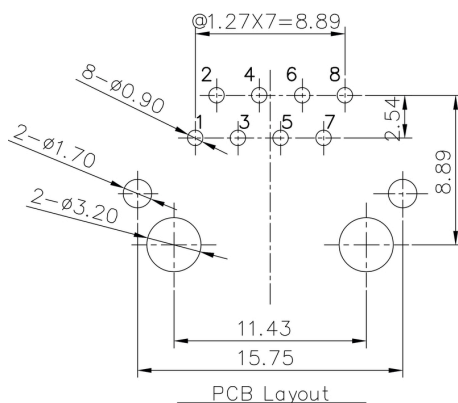
Dimensioned drawing



Dimensioned drawing



PCB design



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www.weidmueller.com**Drawings**

RJ45	G1	R	1	U	3.2	E	4	GY/GY	TY	RJ45G1 R1U 3.2E4GY/GY TY
										Packaging
										TY
										Tray in box (manual assembly)
										Tape on Reel (automated assembly)
										LED
										Y/G
										Yellow/Green
										G/Y
										Green/Yellow (standard)
										GY/GY
										Green-Yellow/Green-Yellow
										O/G
										Orange/Green
										R/O
										Red/Orange
										... (further combinations possible)
										N
										without LED
										Contact surface thickness
										4
										1 = 3µ", 2 = 6µ", 3 = 15µ", 4 = 30µ", 5 = 50µ"
										EMI tabs (ground fingers)
										E
										E = with EMI tabs
										N
										N = without EMI tabs
										Solder Pin length
										3.2
										3.2 mm
										1.6
										1.6 mm
										D
										SMD
										Direction, latch style
										U
										Horizontal (90°, side entry), latch up
										D
										Horizontal (90°, side entry), latch down
										V
										Vertical (180°, top entry)
										Y
										Diagonal (45°), latch up
										Number of Ports
										1
										1 Port
										12; 14; ...
										multi ports side by side, Multiport
										21; 41; ...
										multi ports about each other, Multilevel
										Assembly on PCB
										R
										Through Hole Reflow - THR
										Soldering process: Wave or Reflow soldering
										S
										Surface Mount Technology - SMT
										Soldering process: Reflow soldering
										T
										Through Hole Technology - THT
										Soldering process: Wave
										Performance Category
										C5
										Category 5
										C6
										Category 6
										C6A
										Category 6A
										C5e
										Category 5e
										M
										10/100 Mbit
										G1
										10/100/1000 Mbit
										G10
										10 Gbit
										U
										Unshielded
										MP
										10/100 Mbit with POE
										MP+
										10/100 Mbit with POE+

Legend

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Catalogue status 26.04.2025 / We reserve the right to make technical changes.

Recommended wave soldering profiles

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Fax: +49 5231 14-292083
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260 °C . In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.